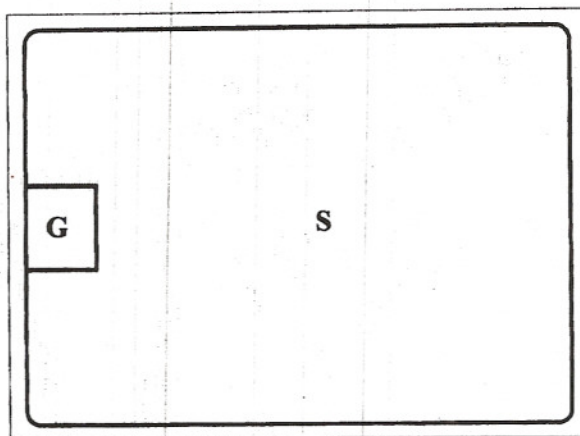




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



NOTE: G = GATE
S = SOURCE
BACKSIDE IS DRAIN

Topside Metal: Aluminum
Backside Metal: V/Ni+Ag
Backside Potential: Drain
Bond Pad Size: .004" min.
Mask Ref: HEX III

APPROVED BY: J Kidd

DIE SIZE : .083" X .100"

DATE: 9/26/07

MFG: Fairchild Semi

THICKNESS: .019"

Part # FQD10N20L